



DUAL N-CHANNEL ENHANCEMENT MODE FIELD EFFECT TRANSISTOR

Features

- **Dual N-Channel MOSFET**
- Low On-Resistance
- Very Low Gate Threshold Voltage, 1.2V max
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- **ESD Protected Gate**
- Lead Free By Design/RoHS Compliant (Note 2)
- "Green" Device (Note 3)

Mechanical Data

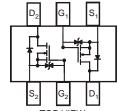
- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.006 grams (approximate)

SOT-563





TOP VIEW



TOP VIEW Schematic and Transistor Diagram

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GSS}	±10	V
Drain Current (Note 1)	I_{D}	400	mA

Thermal Characteristics @TA = 25°C unless otherwise specified

Total Power Dissipation (Note 1)	P_{D}	400	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ heta JA}$	313	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 4)								
Drain-Source Breakdown Voltage		BV_{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	@ $T_C = 25^{\circ}C$	I _{DSS}	_	_	1	μА	$V_{DS} = 30V, V_{GS} = 0V$	
Gate-Body Leakage		loss	_		±10	μΑ	$V_{GS} = \pm 10V$, $V_{DS} = 0V$	
Gate Body Leakage		I _{GSS}			±500	nA	$V_{GS} = \pm 5V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 4)								
Gate Threshold Voltage		$V_{GS(th)}$	0.6	_	1.2	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
			_	_	2.2		$V_{GS} = 1.8V, I_D = 20mA$	
Static Drain-Source On-Resistance		R _{DS (ON)}	_	_	1.5	Ω	$V_{GS} = 2.5V, I_D = 20mA$	
			_		1.2		$V_{GS} = 4.0V, I_D = 100mA$	
Forward Transconductance		Y _{fs}	100	_	_	mS	$V_{DS} = 10V, I_{D} = 0.1A$	
Source-Drain Diode Forward Voltage			0.5	_	1.4	V	$V_{GS} = 0V, I_{S} = 115mA$	
DYNAMIC CHARACTERISTICS								
Input Capacitance			_	39	_	pF	., ., ., ., .,	
Output Capacitance			_	10	_	pF	$V_{DS} = 3V$, $V_{GS} = 0V$ f = 1.0MHz	
Reverse Transfer Capacitance			_	3.6	_	pF	= 1.0ΙVΙΠΖ	
Switching Time	Turn-on Time	t _{on}	_	11	_	nS	$V_{DD} = 5V, I_D = 10 \text{ mA},$	
Switching Time	Turn-off Time	t _{off}	_	51	_	nS	$V_{GS} = 5V$	

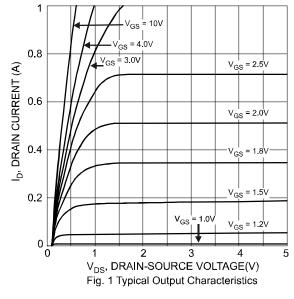
1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which Notes: can be found on our website at http://www.diodes.com.

No purposefully added lead.

Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.

4. Short duration pulse test used to minimize self-heating effect.





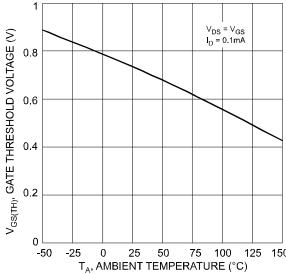


Fig. 3 Gate Threshold Voltage vs. Ambient Temperature

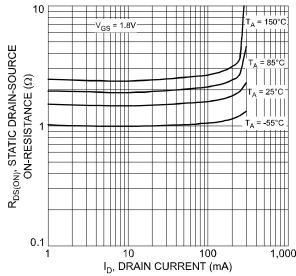
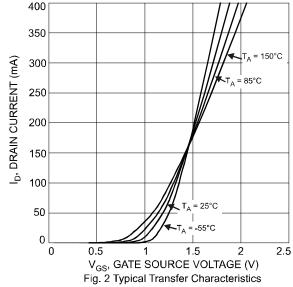


Fig. 5 Static Drain-Source On-Resistance vs. Drain Current



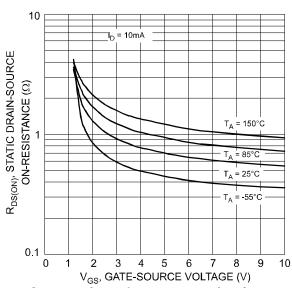


Fig. 4 Static Drain-Source On-Resistance vs. Gate-Source Voltage

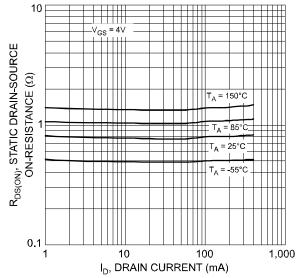
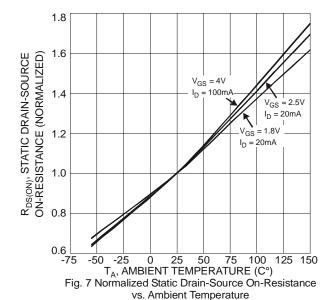


Fig. 6 Static Drain-Source On-Resistance vs. Drain Current





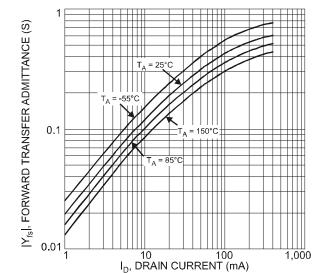
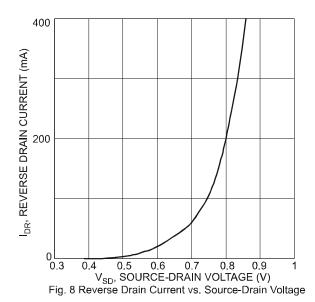


Fig. 9 Forward Transfer Admittance vs. Drain Current



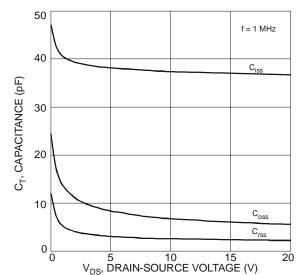


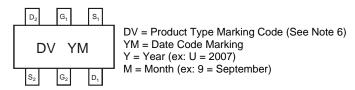
Fig. 10 Typical Capacitance

Ordering Information (Note 5)

Part Number	Case	Packaging
DMN32D2LV-7	SOT-563	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information (Note 6)



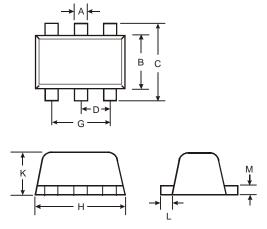
Notes: 6. Package is non-polarized. Parts may be on reel in orientation illustrated, 180° rotated, or mixed (both ways).

Date Code Key

Bate Code Hoy													
Year	20	07	20	2008		2009		2010		2011		2012	
Code	Į	J	\	/	٧	V		(\	1	Z	7	
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec	
Code	1	2	3	4	5	6	7	8	9	0	N	D	

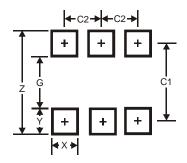


Package Outline Dimensions



SOT-563					
Dim	Min	Max	Тур		
Α	0.15	0.30	0.20		
В	1.10	1.25	1.20		
С	1.55	1.70	1.60		
D	-	-	0.50		
G	0.90	1.10	1.00		
Н	1.50	1.70	1.60		
K 0.55		0.60	0.60		
L	0.10	0.30	0.20		
М	0.10	0.18	0.11		
All	All Dimensions in mm				

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5



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